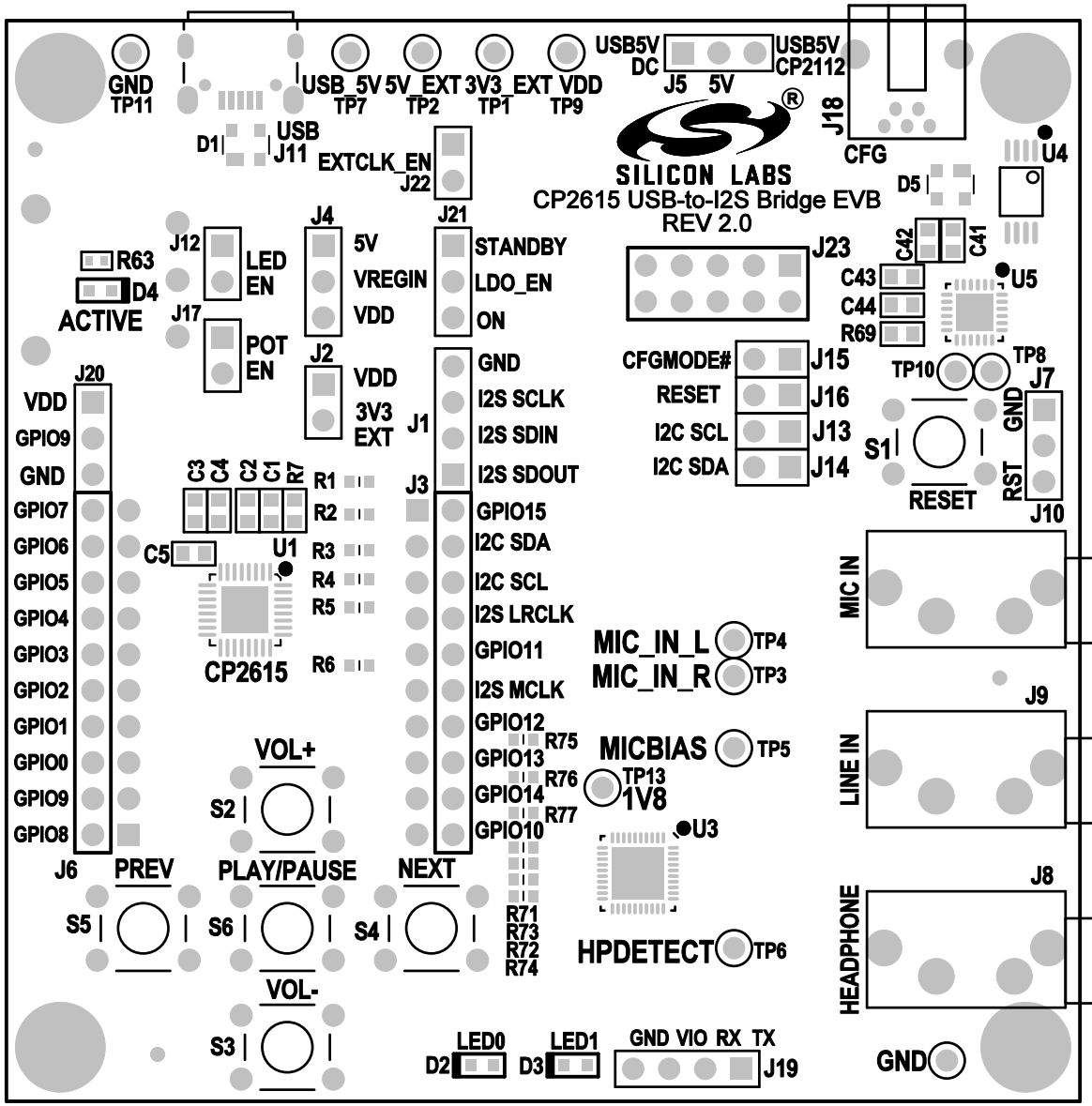
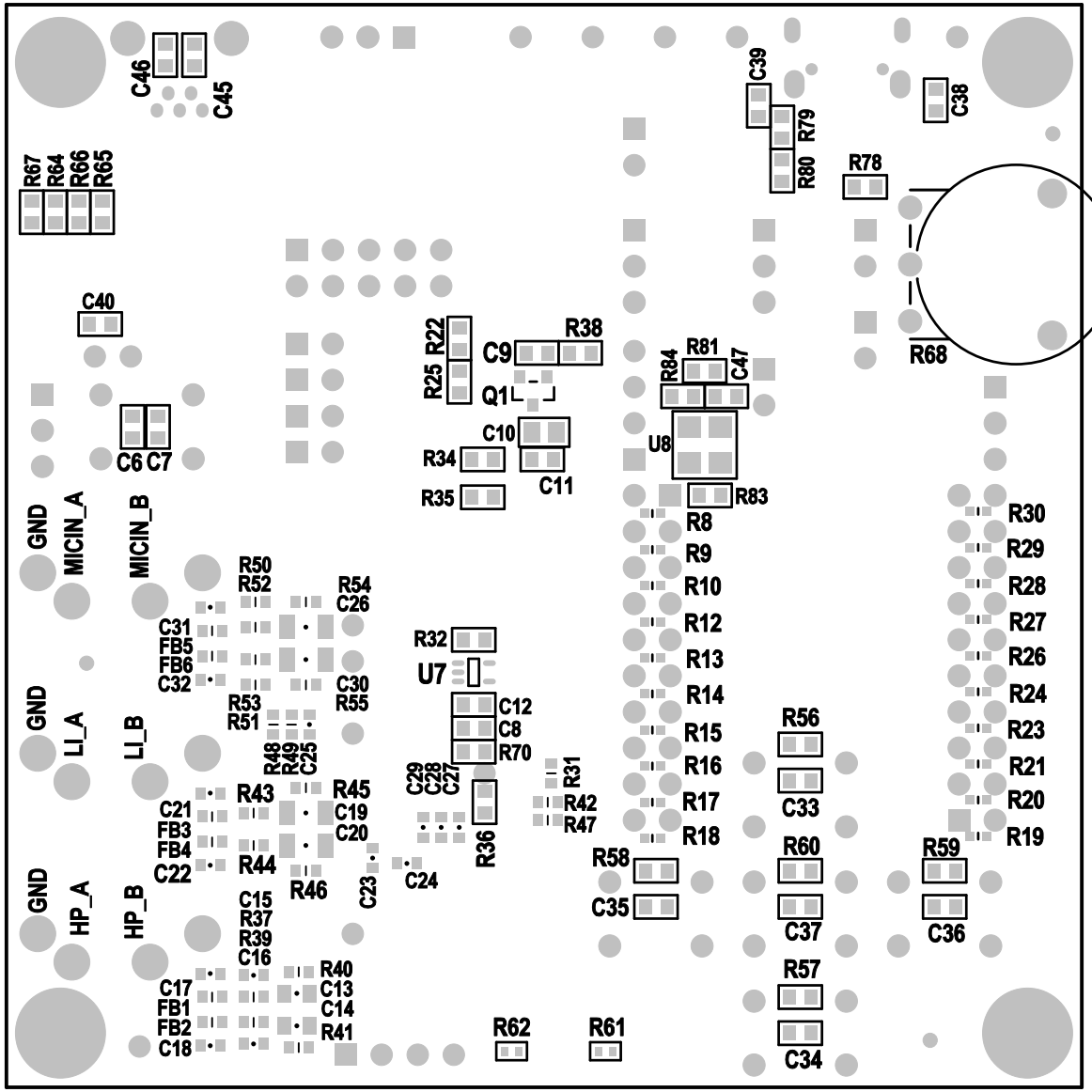
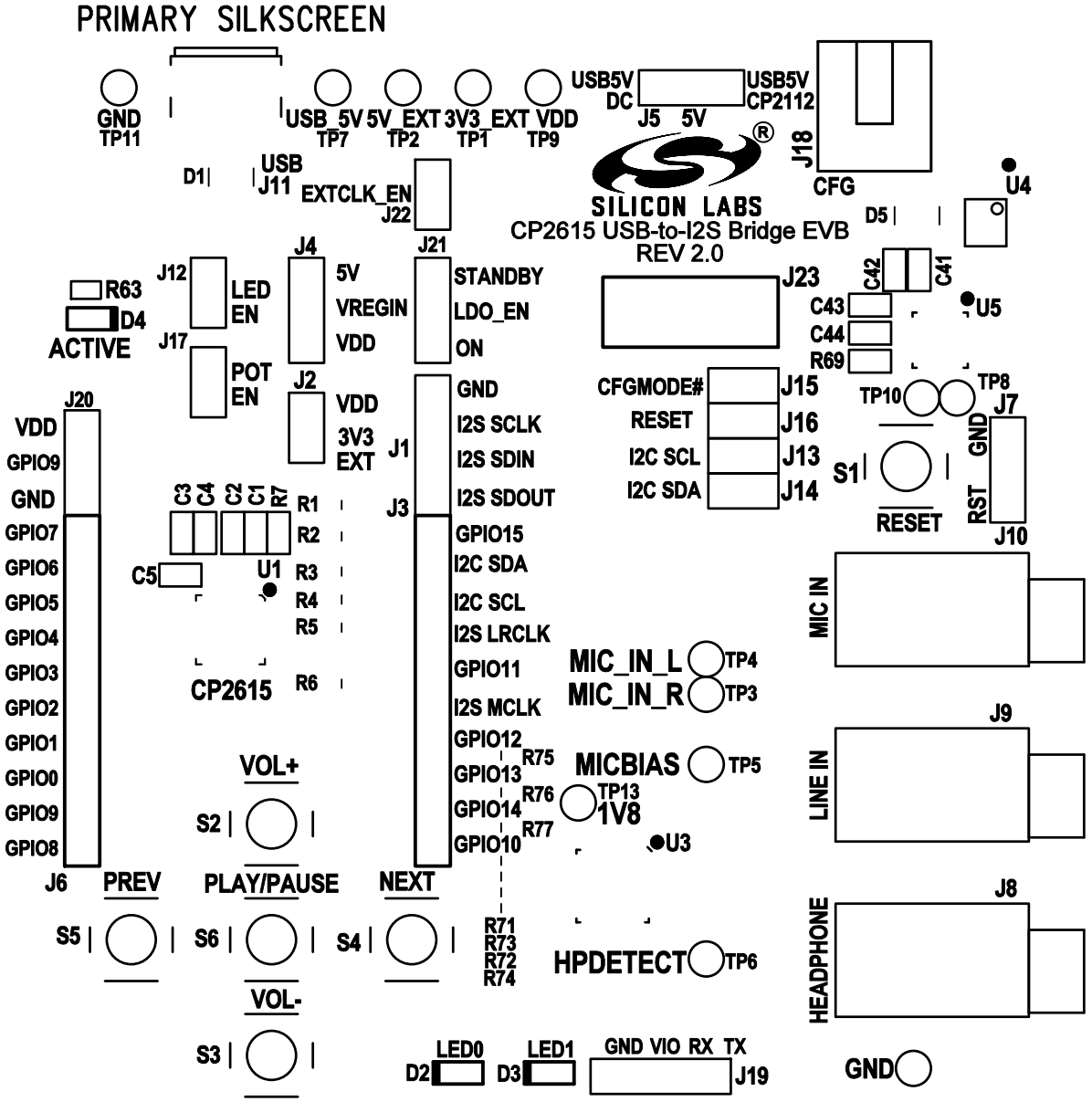
PRIMARY SILKSCREEN

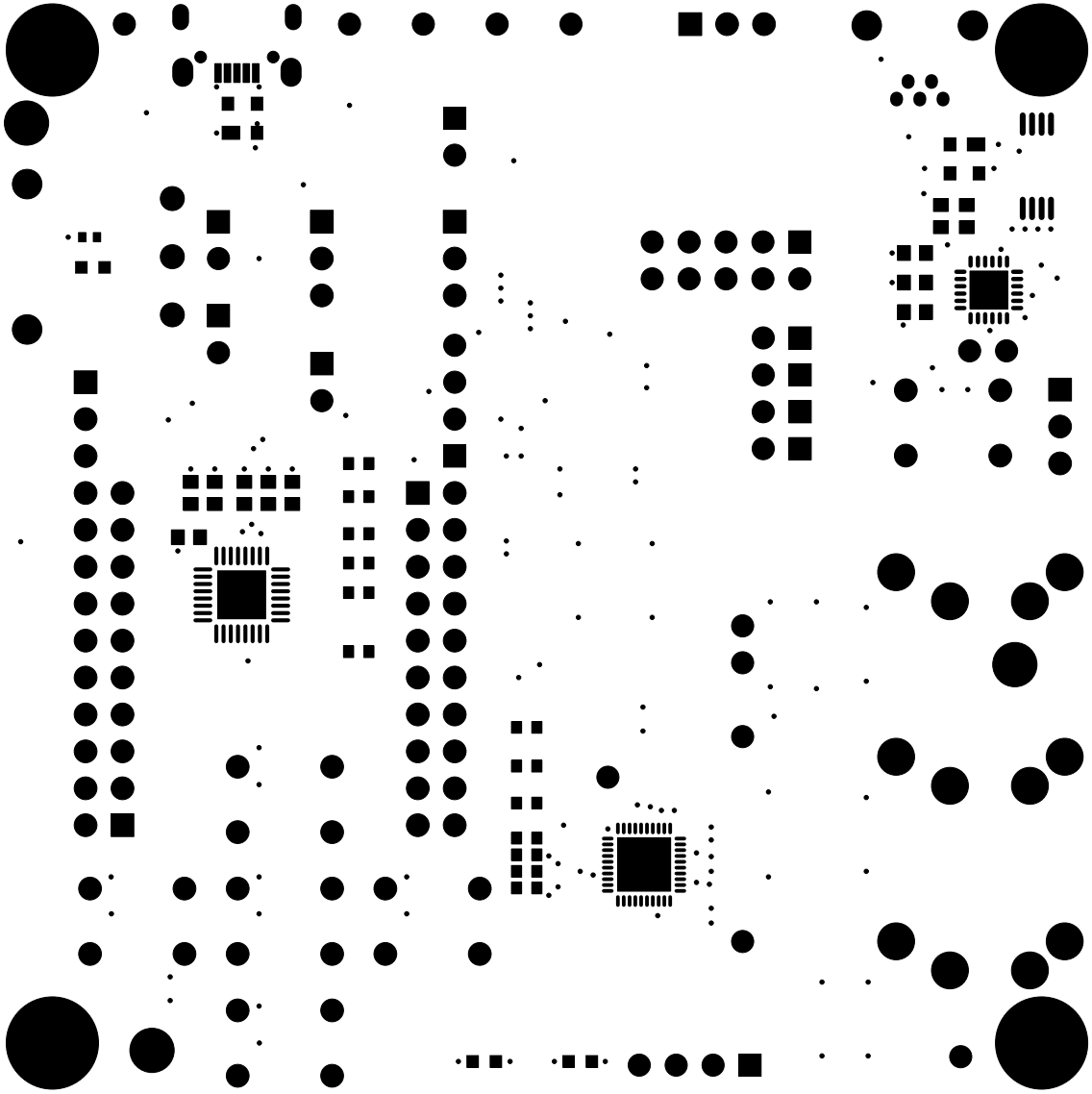


SECONDARY SILKSCREEN

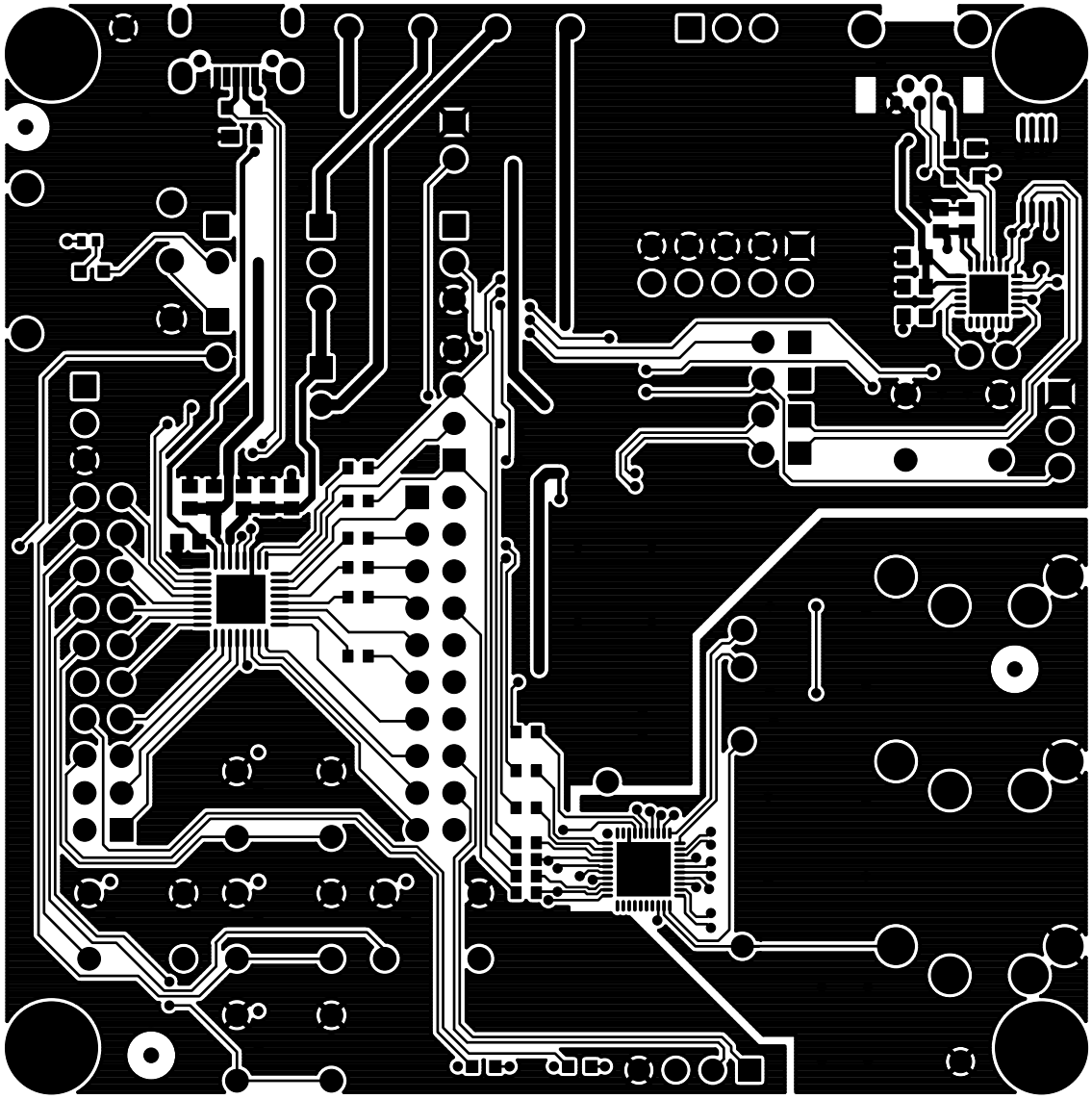



PRIMARY SILKSCREEN
GND
TP11
USB_5V
TP7
5V_EXT
TP2
3V3_EXT
TP1
VDD
TP9
USB5V
DC
J5 5V
USB5V
CP2112
J18
CFG
U4
D1
USB
J11
EXTCLK_EN
J22
SILICON LABS
CP2615 USB-to-I2S Bridge EVB
REV 2.0
D5
J4
J21
J12
LED
EN
5V
VREGIN
VDD
STANDBY
LDO_EN
ON
J23
C42
C41
C43
C44
R69
U5
R63
D4
ACTIVE
J17
POT
EN
J2
VDD
3V3
EXT
GND
I2S SCLK
I2S SDIN
I2S SDOUT
CFGMODE#
RESET
I2C SCL
I2C SDA
J15
J16
J13
J14
TP10
TP8
J7
GND
RST
S1
RESET
J20
VDD
GPIO9
GND
GPIO7
GPIO6
GPIO5
GPIO4
GPIO3
GPIO2
GPIO1
GPIO0
GPIO9
GPIO8
J1
J3
C3
C4
C2
C1
R7
R1
R2
R3
R4
R5
R6
C5
U1
CP2615
GPIO15
I2C SDA
I2C SCL
I2S LRCLK
GPIO11
I2S MCLK
GPIO12
GPIO13
GPIO14
GPIO10
R75
R76
R77
MIC_IN_L
MIC_IN_R
TP4
TP3
MICBIAS
TP5
TP13
1V8
U3
J10
MIC IN
J9
LINE IN
J8
HEADPHONE
GND
VOL+
S2
VOL-
S3
J6
PREV
S5
PLAY/PAUSE
S6
NEXT
S4
R71
R73
R72
R74
HPDETECT
TP6
LED0
D2
LED1
D3
GND VIO RX TX
J19

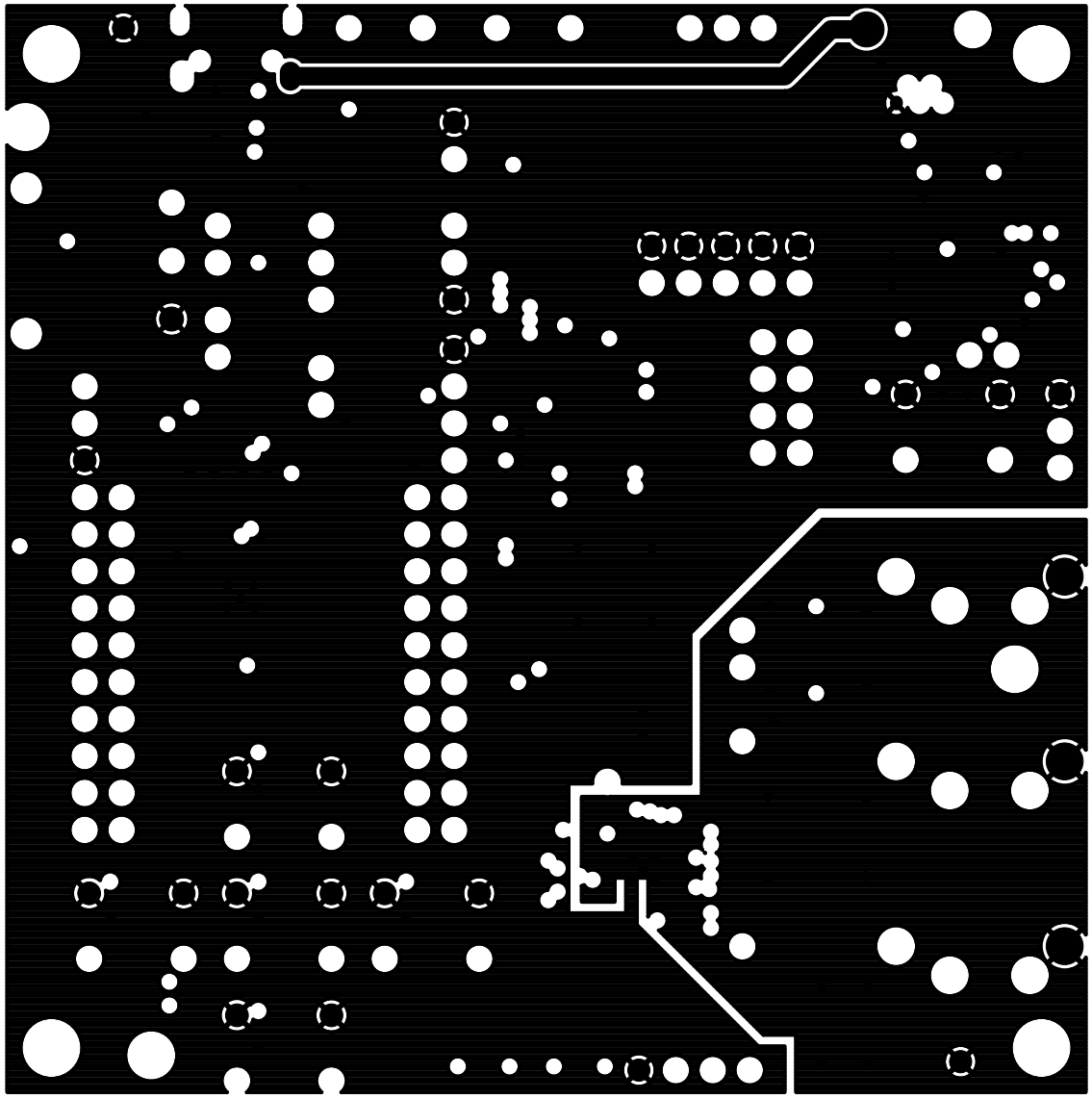
PRIMARY SOLDER MASK



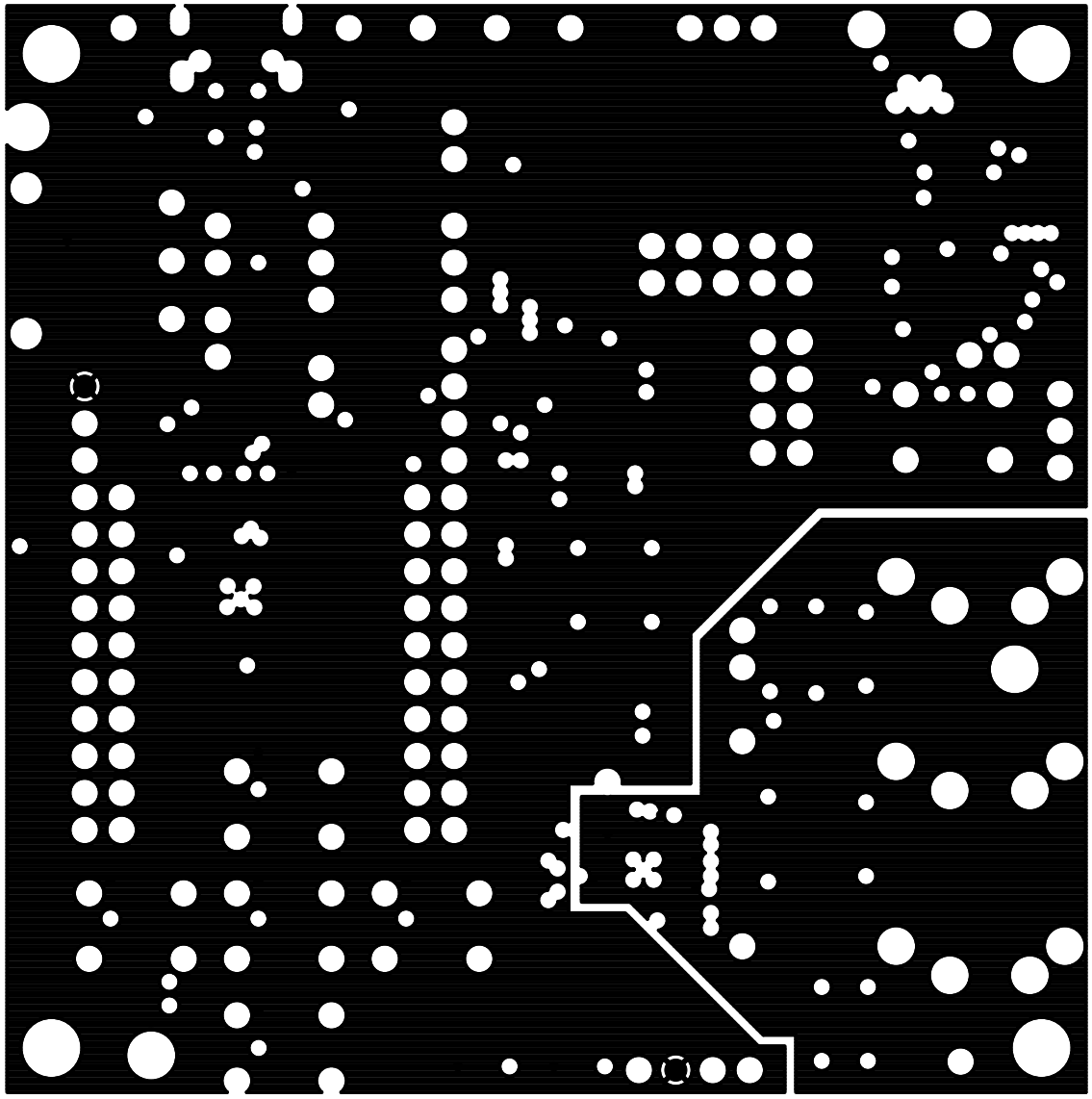
PRIMARY SIDE



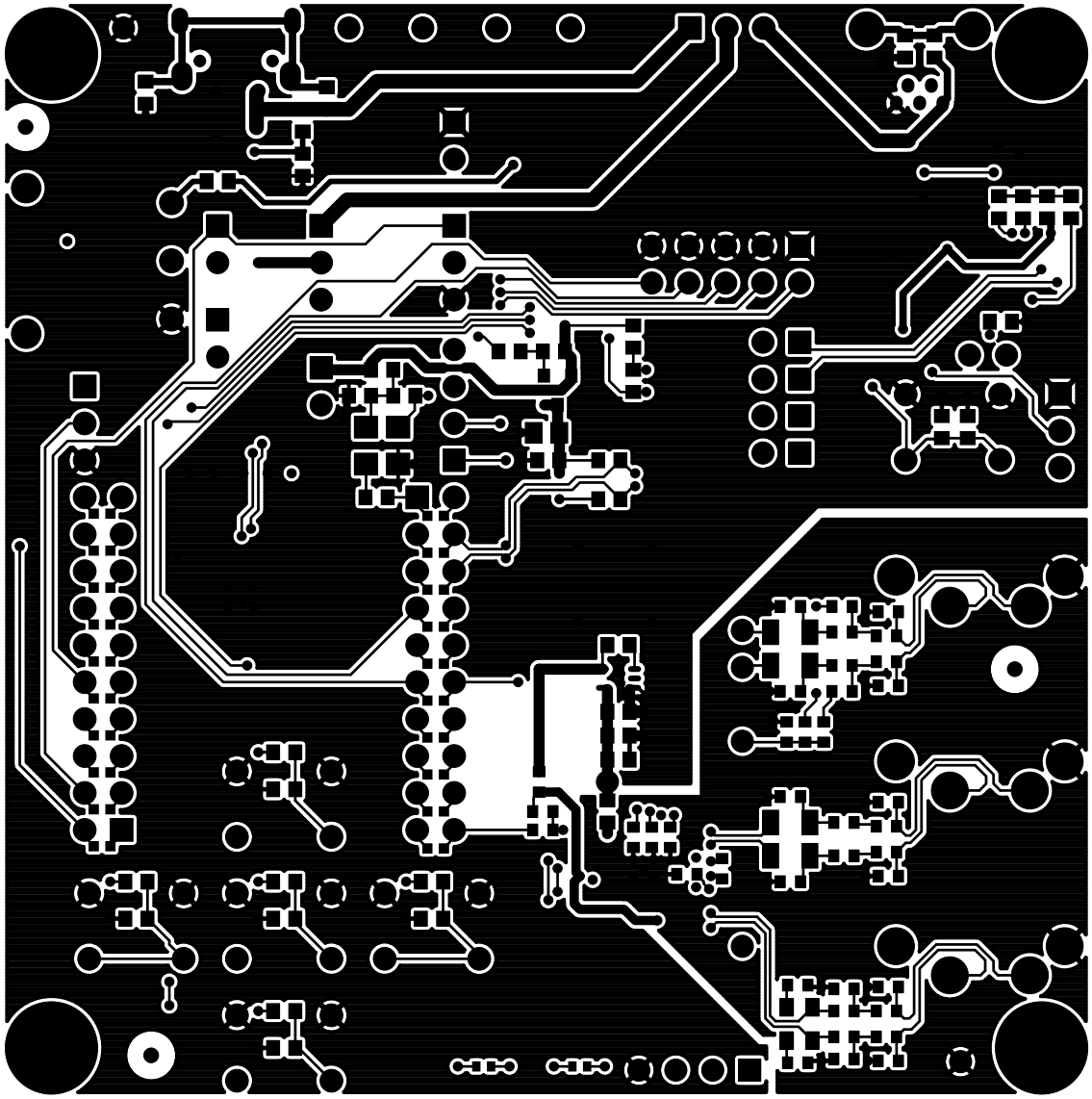
GROUND PLANE



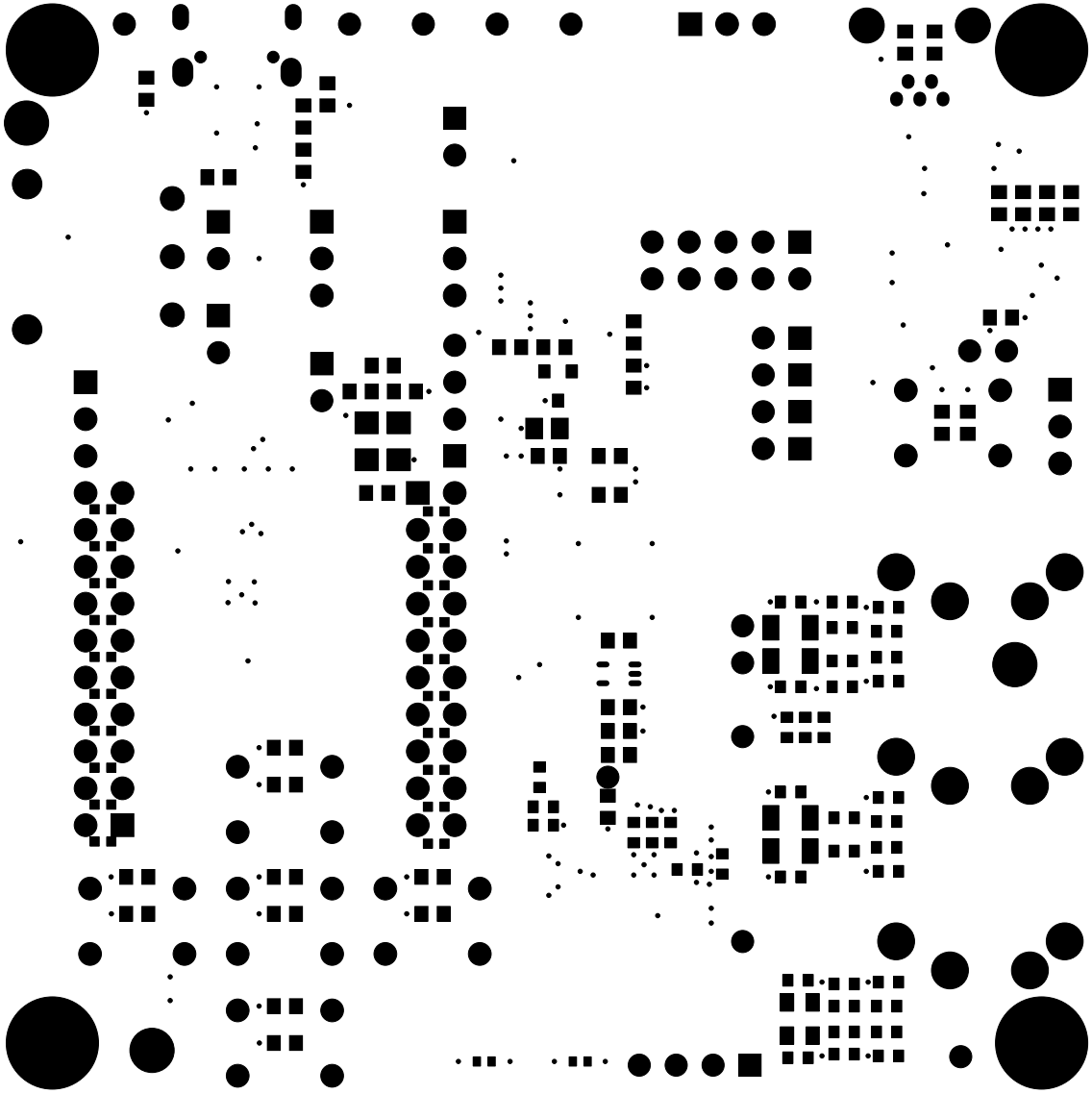
POWER PLANE



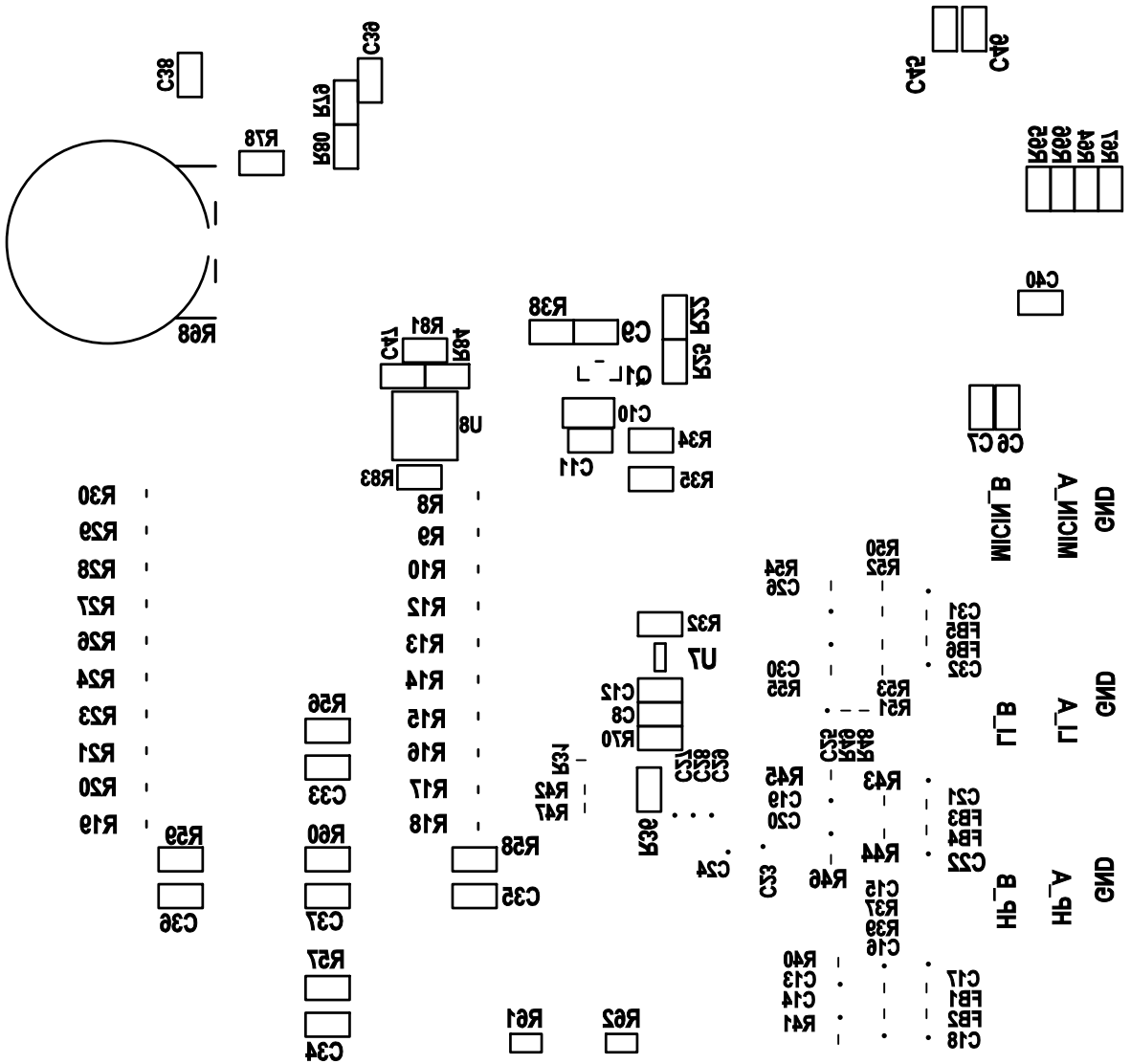
SECONDARY SIDE



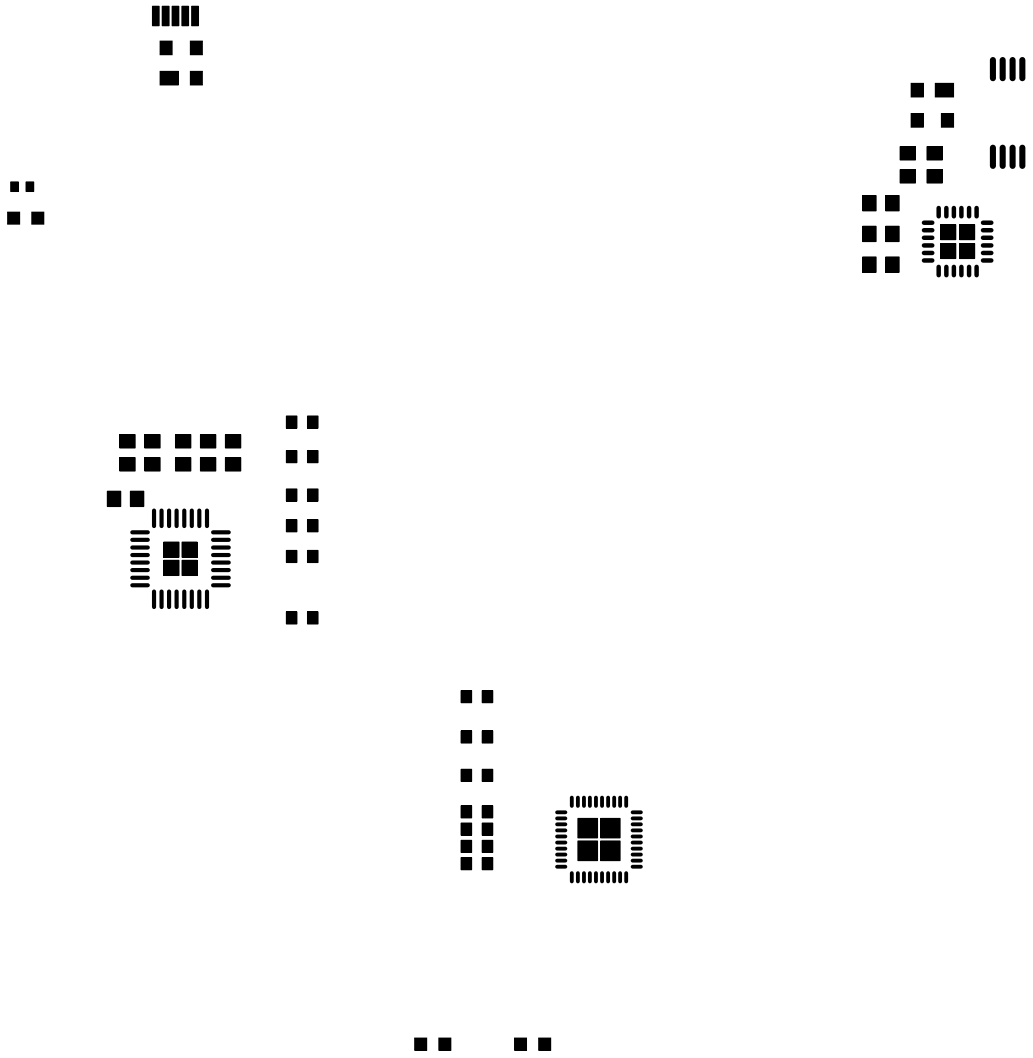
SECONDARY SOLDER MASK



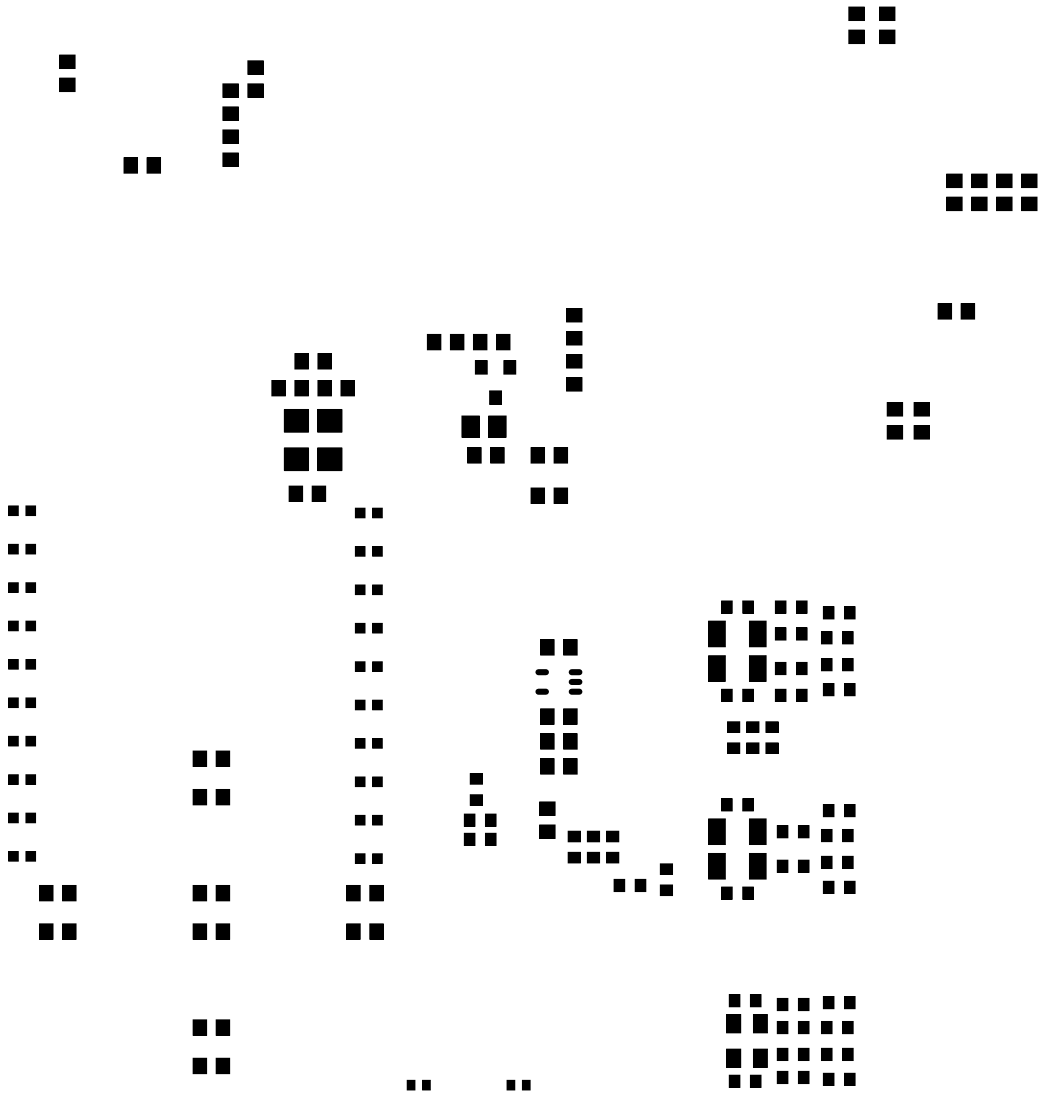
SECONDARY SILKSCREEN

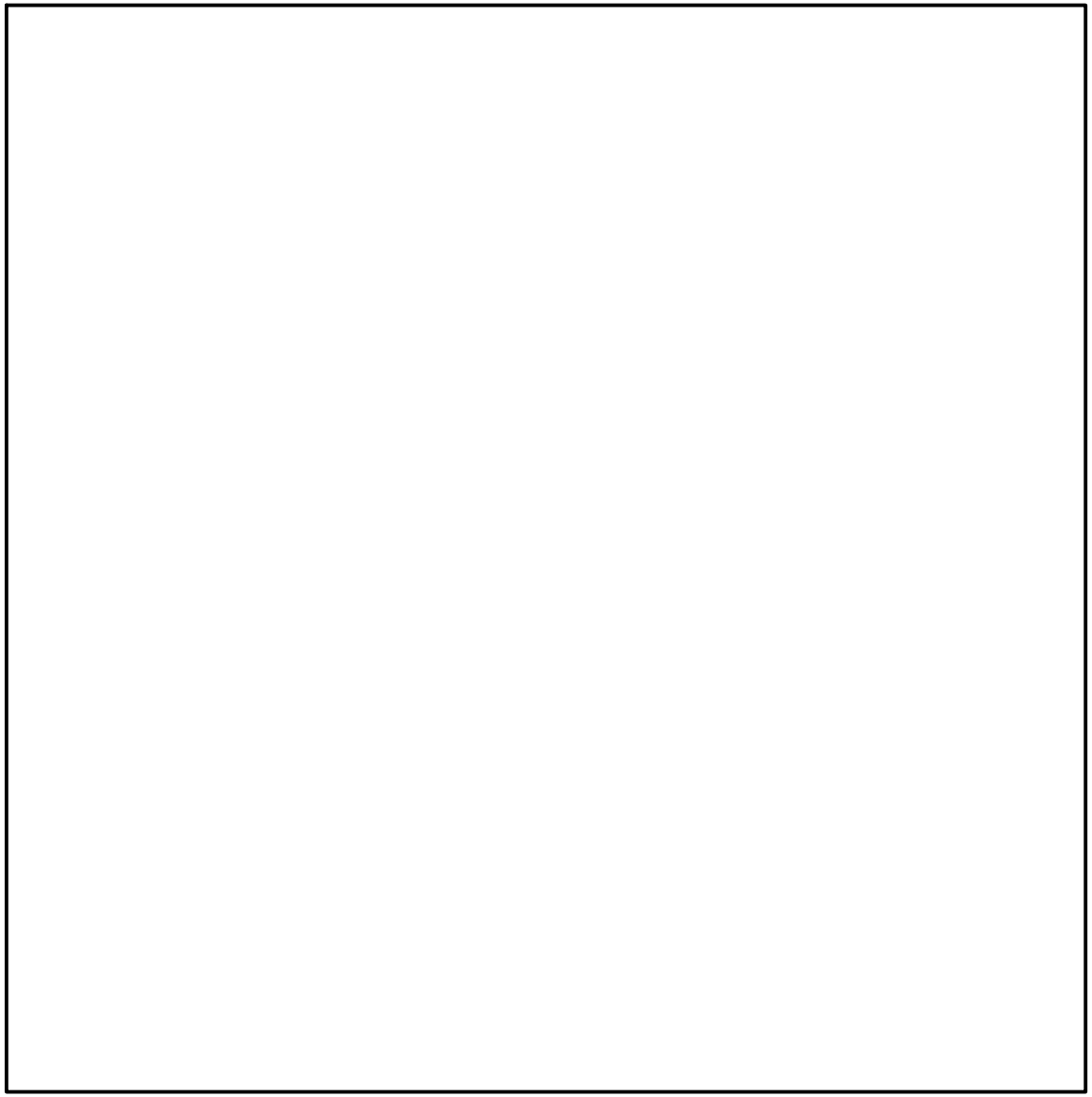


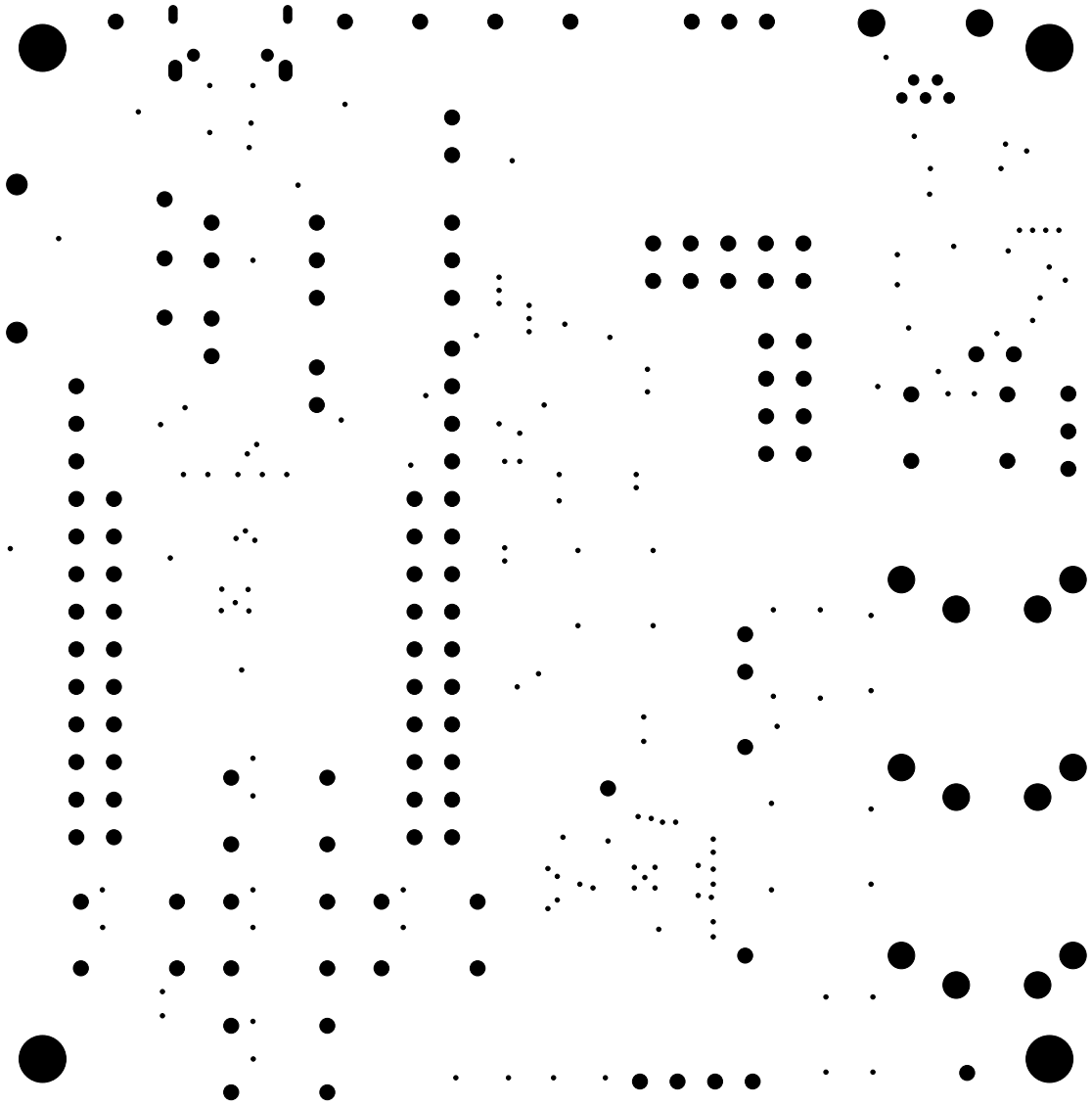
PRIMARY SOLDER PASTE



SECONDARY SOLDER PASTE



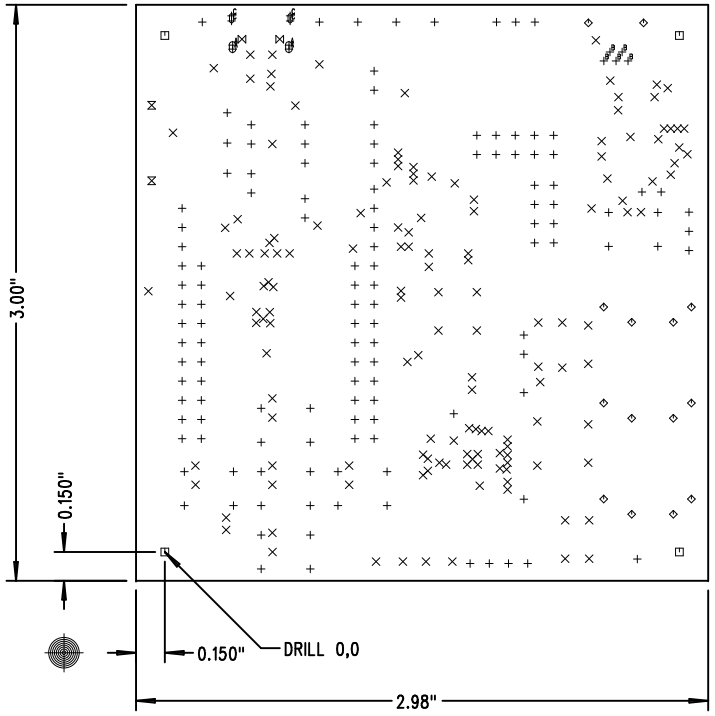




NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE >= 345°C, COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 0.5 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ±0.003".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" +/- 0.004" ACROSS PADS.
10. WARP/TWIST SHALL NOT EXCEED 0.010 INCH PER INCH.
11. FINISH SHALL BE LPI, BLUE S.M.O.B.C., PLATE ENIG BOTH SIDES.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. NO VENDOR MARKINGS OR ALTERATIONS SHALL BE PERMITTED ON ANY METAL OR SILKSCREEN LAYERS.
14. DO NOT CLEAR SILKSCREEN FROM VIA PADS.
    A MINIMAL SILKSCREEN CLEARANCE FROM VIA HOLES IS ACCEPTABLE.

PRIMARY DRILL



LAYER STACKUP	FILE NAMES
PRIMARY SILKSCREEN	CP2615_PSS.PHO
PRIMARY SOLDERMASK	CP2615_PSM.PHO
PRIMARY SIDE	CP2615_PRI.PHO
GROUND PLANE	CP2615_L02.PHO
POWER PLANE	CP2615_L03.PHO
SECONDARY SIDE	CP2615_SEC.PHO
SECONDARY SOLDERMASK	CP2615_SSM.PHO
SECONDARY SILKSCREEN	CP2615_SSS.PHO

SCALE: NONE

SIZE	QTY	SYM	PLATED	TOL
0.04	129	+	YES	+/-0.003
0.012	147	X	YES	+0/-0.012
0.125	4	□	YES	+/-0.003
0.071	14	◇	YES	+/-0.003
0.055	2	⧖	YES	+/-0.003
0.032	2	⋈	NO	+/-0.003
0.034 x 0.055	2	+A	YES	+/-0.003
0.028	5	+B	YES	+/-0.003
0.022 x 0.048	2	+C	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH
DIMENSIONS IN BRACKETS [ ] ARE IN MILLIMETERS
INTERPRET DRAWING PER MIL-D-1000

TOLERANCES

HOLE TOLERANCES PER 78027

DECIMALS	ANGLES	SURFACES
.XX +/- .XXX +/-	+/-	MICROINCHES

PART TO BE FREE OF BURRS

BREAK EDGES	BEND RADIUS	BEND RELIEF
MAX	MAX	MAX

DESIGN	MC	13FEB2018
LAYOUT	CT	13FEB2018

DO NOT SCALE DRAWING

COMPANY: SILICON LABORATORIES
400 W Cesar Chavez
AUSTIN, TX 78701
(512)416-8500
www.silabs.com

NAME: CP2615 USB-to-I2S Bridge EVB

REV : 2.0

SIZE: A

PART NUMBER: .

SCALE 1:1 | FABRICATION DRAWING | SHEET 1 OF 1